

Multi-Channel Silicon ESD Protector Overvoltage Protection Device

DOCUMENT: SCD28190
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Specification Status: Preliminary

BENEFITS

- Industry-leading lowest capacitance; provides lowest insertion loss for high speed data signals
- Industry's smallest footprint and lowest profile multi-channel ESD array helps to optimize board space
- Flow-through and single connection design helps routing PCB matched impedance high speed data lines
- Helps protect electronic circuits against damage from Electrostatic Discharge (ESD), surge and cable discharge events
- Assists equipment to pass IEC61000-4-2, level 4 testing



FEATURES

- Low capacitance: 0.20 pF (typ)
- Low leakage current: 50nA @ 5V (max)
- Low clamping voltage: +9.18 / -0.8V (typ) @ (tp=8x20µs, Ipp=2A)
- ESD maximum rating per IEC61000-4-2 standard:
 - ± 20kV contact discharge
 - ± 20kV air discharge
- Surge: 2A (max) @ (tp=8x20µs) per IEC61000-4-2-5
- Small size and low profile: XDFN array packages 0.31mm height

APPLICATIONS

- Consumer, mobile and portable electronics
- Tablet PC and external storage with high speed interfaces
- Ultra-high speed data lines
- USB 3.0/2.0, HDMI 1.3/1.4, DisplayPort, Thunderbolt (Light Peak), V-by-One HS, and LVDS interfaces
- Applications requiring high ESD performance in small DFN packages

MATERIALS INFORMATION

RoHS Compliant ELV Compliant Halogen Free * Lead Free

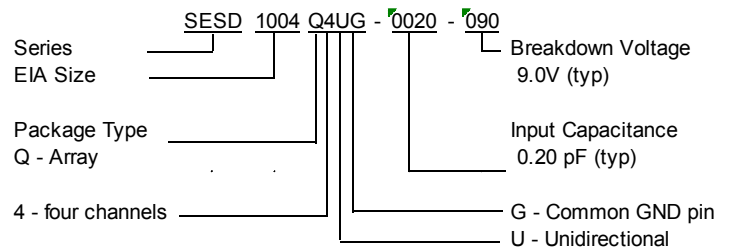
Directive 2000/53/EC Compliant

Directive 2002/95/EC Compliant

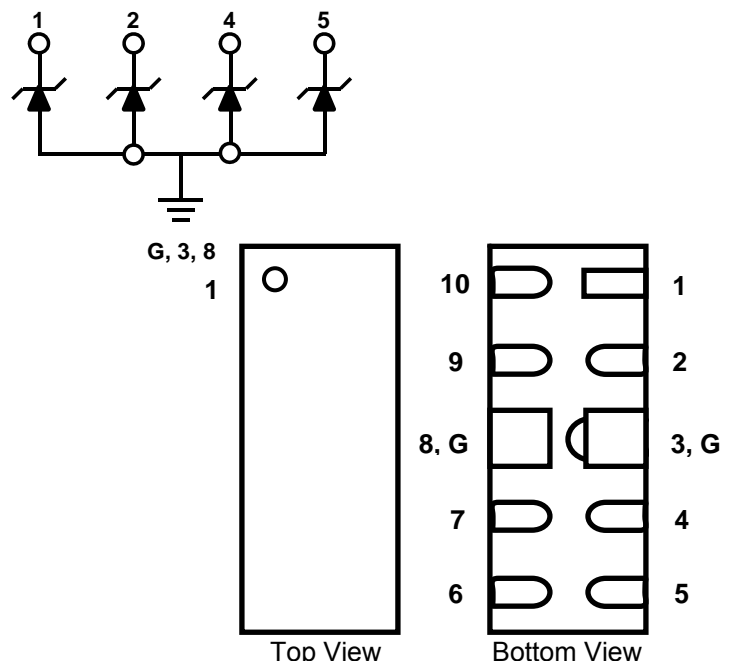


* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm
SESD devices meet MSL-1 Requirements
DFN case epoxy meets UL 94 V-0

PART NUMBERING



SCHEMATIC AND PIN CONFIGURATION



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DEVICE MAXIMUM RATING

ESD Withstand ⁽¹⁾ (IEC 61000-4-2, level 4)		Temperature		Peak Current (tp=8x20µs)
Contact (kV)	Air (kV)	Operating (°C)	Storage (°C)	I _{pp} (A)
± 20	± 20	-55 to +125	-55 to +150	2.0

⁽¹⁾ 20kV @ ± 1 pulse; 10kV @ ± 50 pulses; 8kV @ 1,000 pulses (under IEC6100-4-2)

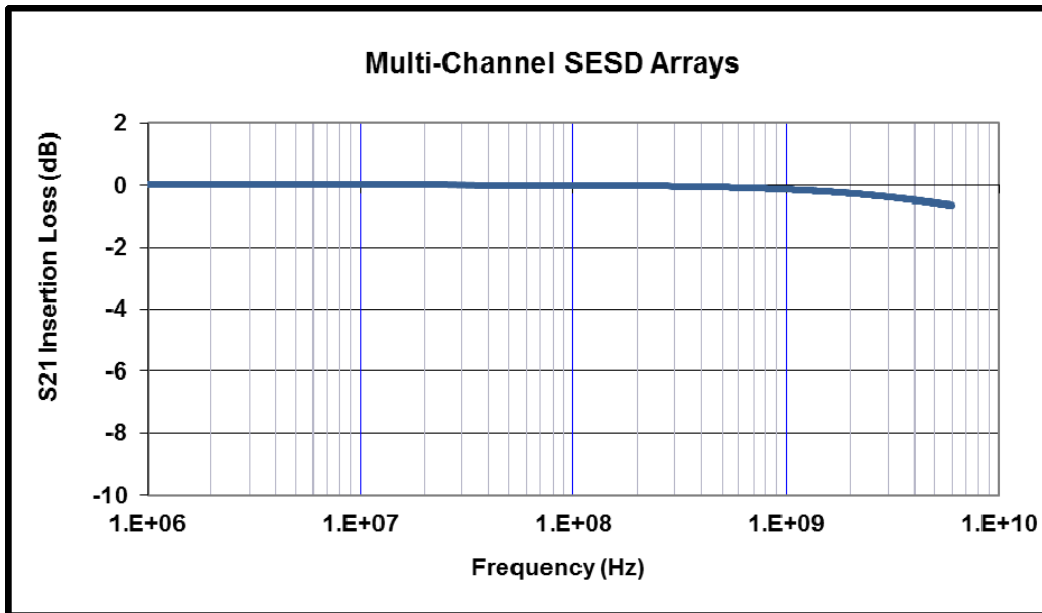
- Device maximum rating @ T = 25°C, unless otherwise specified
- Caution: Stress exceeding Device Maximum Ratings may damage the device
Prolonged exposure to stresses above the Recommended Operating Conditions may affect device reliability

DEVICE ELECTRICAL CHARACTERISTICS

Input Capacitance @ V _R = 0V, f = 3GHz, I/O to GND (pF)		Breakdown Voltage V _{BR} @ I _T =1mA (V)	Reverse Working Voltage (V)		Reverse Leakage Current I _L @ V _{WRV} =5.0V (nA)		Clamping Voltage V _{CL} @ I _{pp} =2.0A (V)
Typ	Maximum	Typ	Min	Max	Typ	Max	Max
0.20	0.22	+9.00 / -0.80	0	+8.00	<5.0	50.0	+9.18 / -0.80

- All device electrical characteristics @ T = 25°C, unless otherwise specified

FIGURE 1. INSERTION LOSS DIAGRAM



Application	Bit Rate (Gbps)	@Freq (GHz)	Ins. Loss (dB)
HDMI 1.4 (1080P)	2.25	1.13	-0.15
DisplayPort	2.70	1.35	-0.20
HDMI 1.4 (max spec)	3.40	1.70	-0.23
USB3.0	5.00	2.50	-0.29
eSATA	6.00	3.00	-0.35
Thunderbolt	10.0	5.00	-0.50

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FIGURE 2. DEVICE IV CURVE

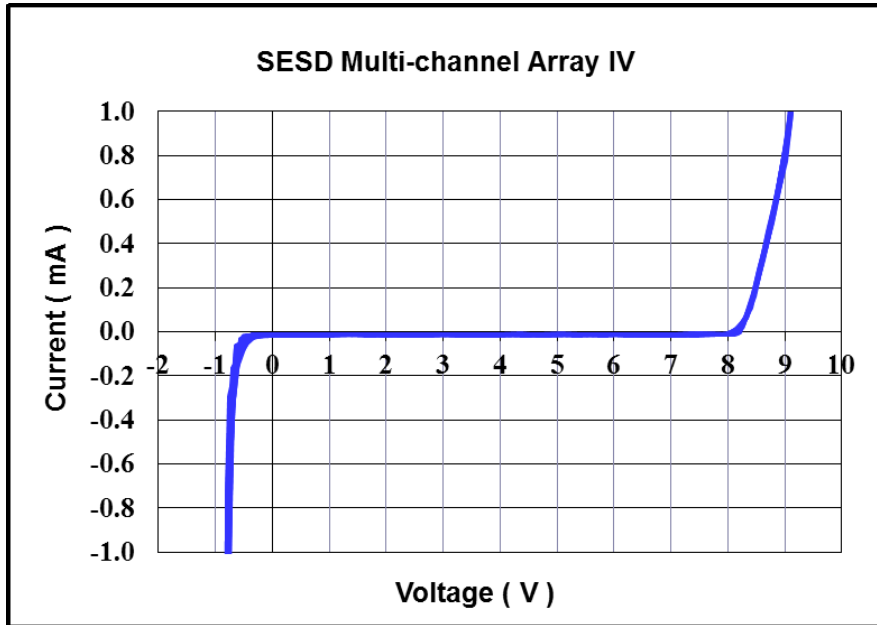
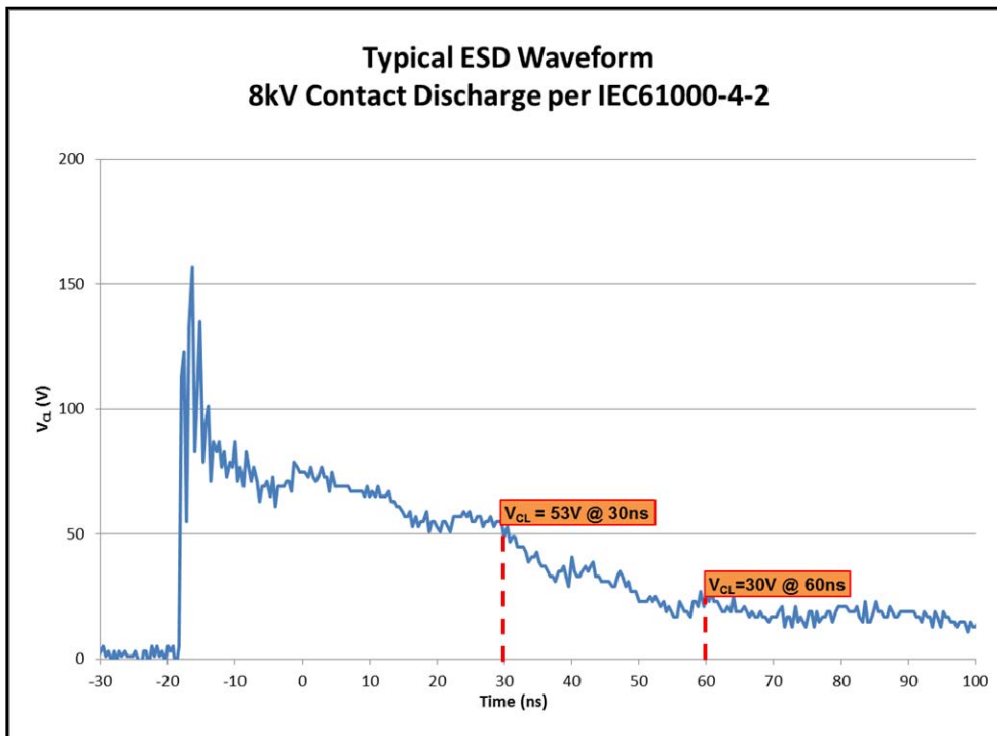
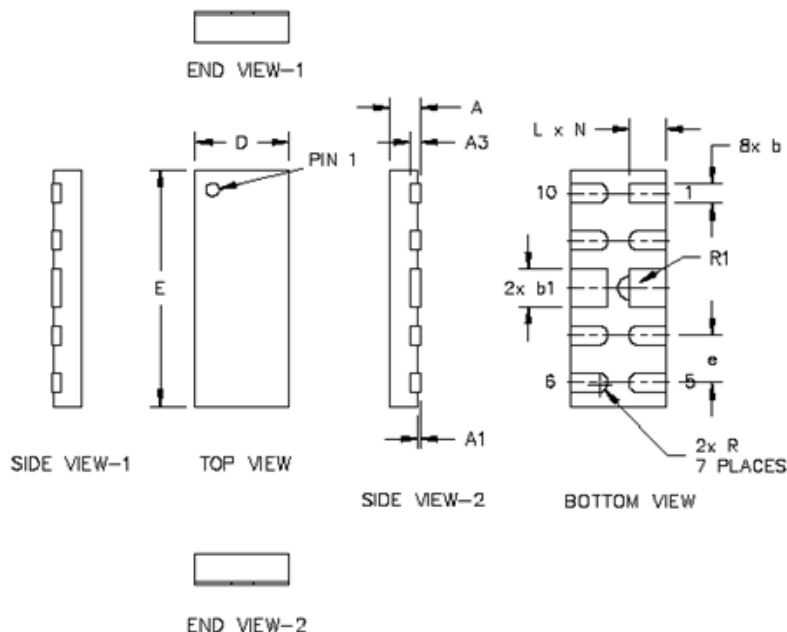


FIGURE 3. ESD WITHSTAND



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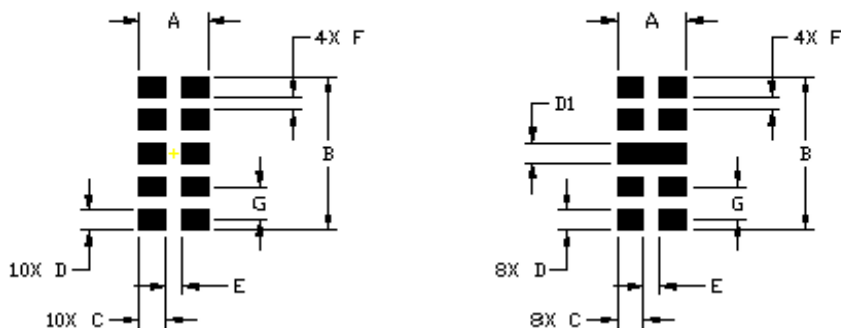
DEVICE DIMENSIONS



SESD1004Q4UG-0020-090						
Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.300	0.310	0.320	0.0118	0.0122	0.0126
A1	0	--	0.050	0	--	0.002
A3	0.10 ref.			0.004 ref.		
D	0.900	1.000	1.100	0.035	0.039	0.043
E	2.400	2.500	2.600	0.094	0.098	0.102
b	0.150	0.200	0.250	0.006	0.008	0.010
b1	0.350	0.400	0.450	0.014	0.016	0.018
L	0.300	0.380	0.425	0.012	0.015	0.017
e	0.500 BSC			0.020 BSC		
N	10			10		
R	0.075 BSC			0.003 BSC		
R1	0.125 BSC			0.005 BSC		

BSC – Basic Spacing between Centers

RECOMMENDED LANDING PATTERN:



SESD Landing Pad Layout		
10 Pin 4-ch Standard FT Array		
Symbol	Millimeters	Inches
A	1.00	0.039
B	2.30	0.091
C	0.38	0.015
D	0.30	0.012
D1	0.30	0.012
E	0.24	0.009
F	0.20	0.008
G	0.50 BSC	0.020 BSC

BSC – Basic Spacing between Centers

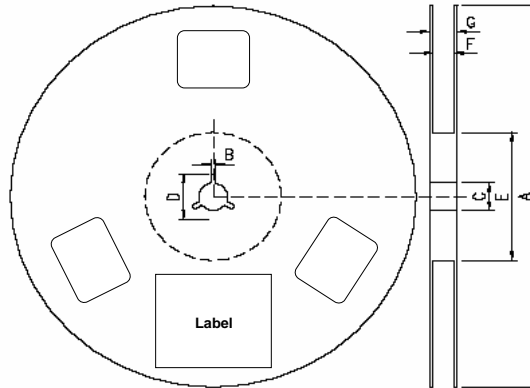
PACKAGING

Packaging	Tape & Reel	Standard Box
SESD1004Q4UG-0020-090	5,000	25,000

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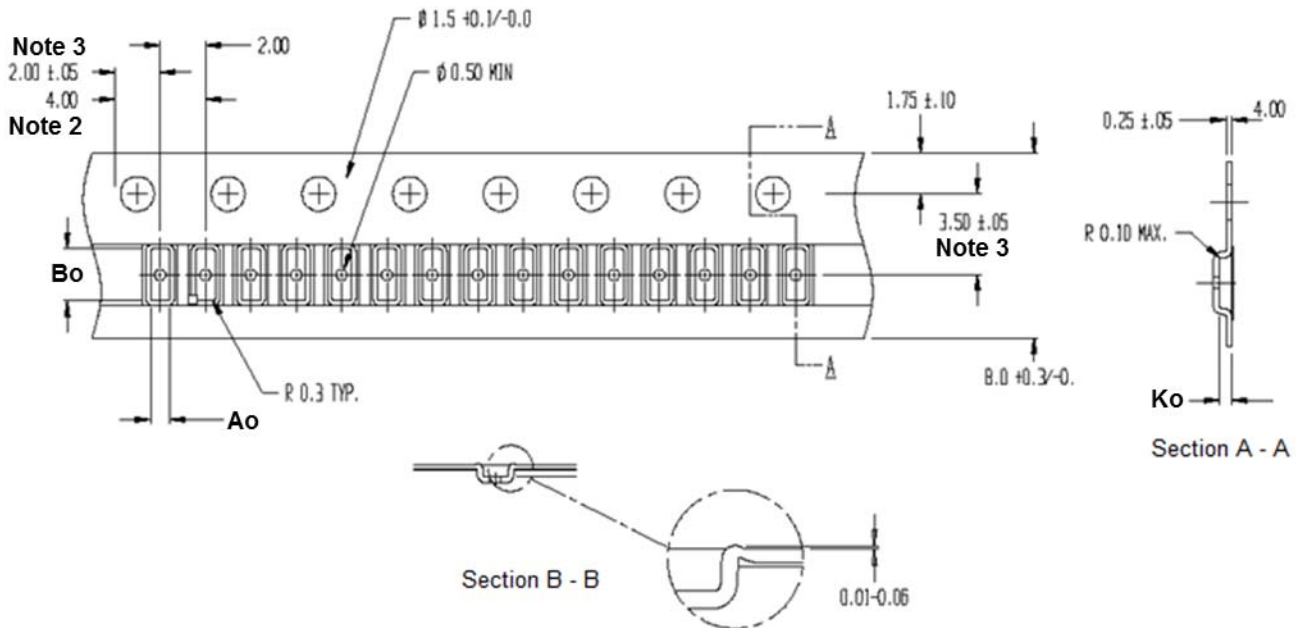
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REEL DIMENSIONS



Dimensions	A	B	C	D	E	F	G
(mm)	180.0 ± 1.5	23.0 ± 0.2	13.0 + 0.5 / -0.2	17.3 ± 0.2	60.5 ± 1.5	8.4 +1.5/-0.0	14.4 (max)

CARRIER TAPE DIMENSIONS



Ao	1.20 ± 0.05
Bo	2.70 ± 0.05
Ko	0.51 ± 0.05

Note 1. All dimensions in mm

Note 2. 10 sprocket hole pitch cumulative tolerance ± 0.2

Note 3. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole

Note 4. Ao and Bo are calculated on a plane at a distance "R" at the bottom of the pocket

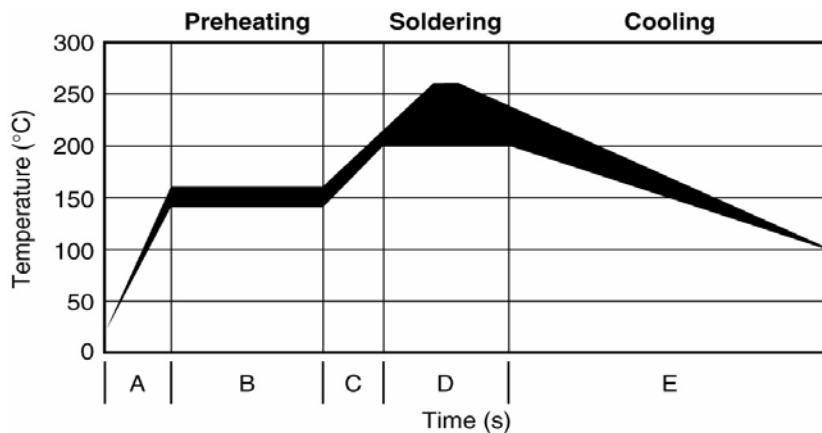
Note 5. Tolerances unless noted 1PL ± 0.20, 2PL ± 0.10

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SOLDER REFLOW RECOMMENDATION

A	Temperature ramp up 1	From ambient to Preheating temperature	30s to 60s
B	Preheating	140°C - 160°C	60s to 120s
C	Temperature ramp up 2	From Preheating to Main heating temperature	20s to 40s
D	Main heating	at 200°C at 220°C at 240°C at 260°C	60s ~ 70s 50s ~ 60s 30s ~ 40s 5s ~ 10s
E	Cooling	From main heating temperature to 100°C	4°C/s (max)

FIGURE 4. REFLOW PROFILE



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